

BOARD CHARACTERISTICS

Copper Layer Count:2Board Thickness:1.6000 mm

Board overall dimensions:40.8940 mm x 101.4730 mm

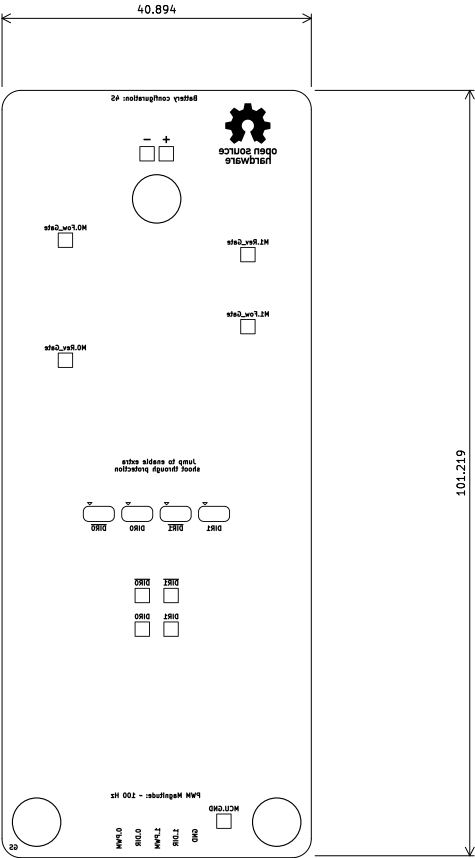
Min track/spacing:0.1000 mm / 0.1000 mmMin hole diameter:0.2500 mm

Copper Finish:NoneImpedance Control:No

Castellated pads:NoPlated Board Edge:No

Edge card connectors:No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



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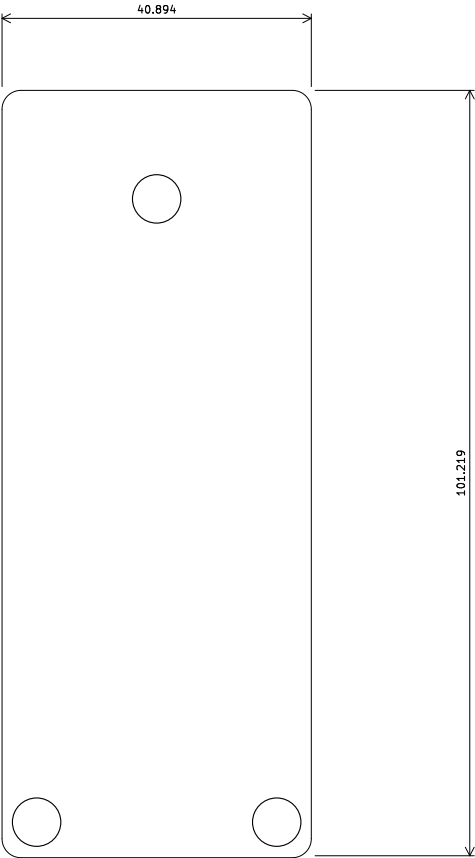
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[illegible]

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40.894

101.219

The PCB layout diagram shows a rectangular board with dimensions 40.894 mm by 101.219 mm. It features a central microcontroller unit (MCU) labeled "T5 DUAL H-BRIDGE Rev A". Surrounding the MCU are various passive components including resistors (R1-R20) and capacitors (C1-C16). Two motors, labeled "Motor1" and "Motor2", are positioned on the left side. Other components include a battery symbol labeled "BATT", an LED or indicator labeled "LT1161", and several integrated circuits or modules labeled "MCT6" and "Q1-Q16". The layout includes mounting holes and component footprints.

George SleenTeam 5

Sheet:
File: dual-h-bridge.kicad_pcb

Title: Dual H-Bridge

Size: A4Date: 2025-06-19

KiCad E.D.A. 9.0.2

Rev: AId: 3/4

Copper Layer Count:
Board overall dimensions:
Min track/spacing:
Copper Finish:
Castellated pads:
Edge card connectors:

2
40.8940 mm x 101.4730 mm
0.1000 mm / 0.1000 mm
None
No
No

Board Thickness:

Min hole diameter:
Impedance Control:
Plated Board Edge:

1.6000 mm

0.2500 mm
No
No

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40.894

Motor1

Q16

R5

10k

R6

100k

Q7

Q3

Q5

C8

BATT

- +

R9

10k

R10

100k

C9

Q13

Q12

C13

Q6

C7

Q14

C14

Motor1

Q4

Q8

Q9

Q10

Q11

Q15

T5

DUAL H-BRIDGE Rev A

R7

10k

R8

100k

R11

10k

R12

100k

C4

C1

LT1161

C2

C5

C6

R16

10k

R14

10k

Q1

MCT6

R2

100k

R4

100k

Q2

MCT6

R13

330R

R15

330R

U2

10k

10k

R19

330R

R17

330R

C10

MCU

R1

10k

R3

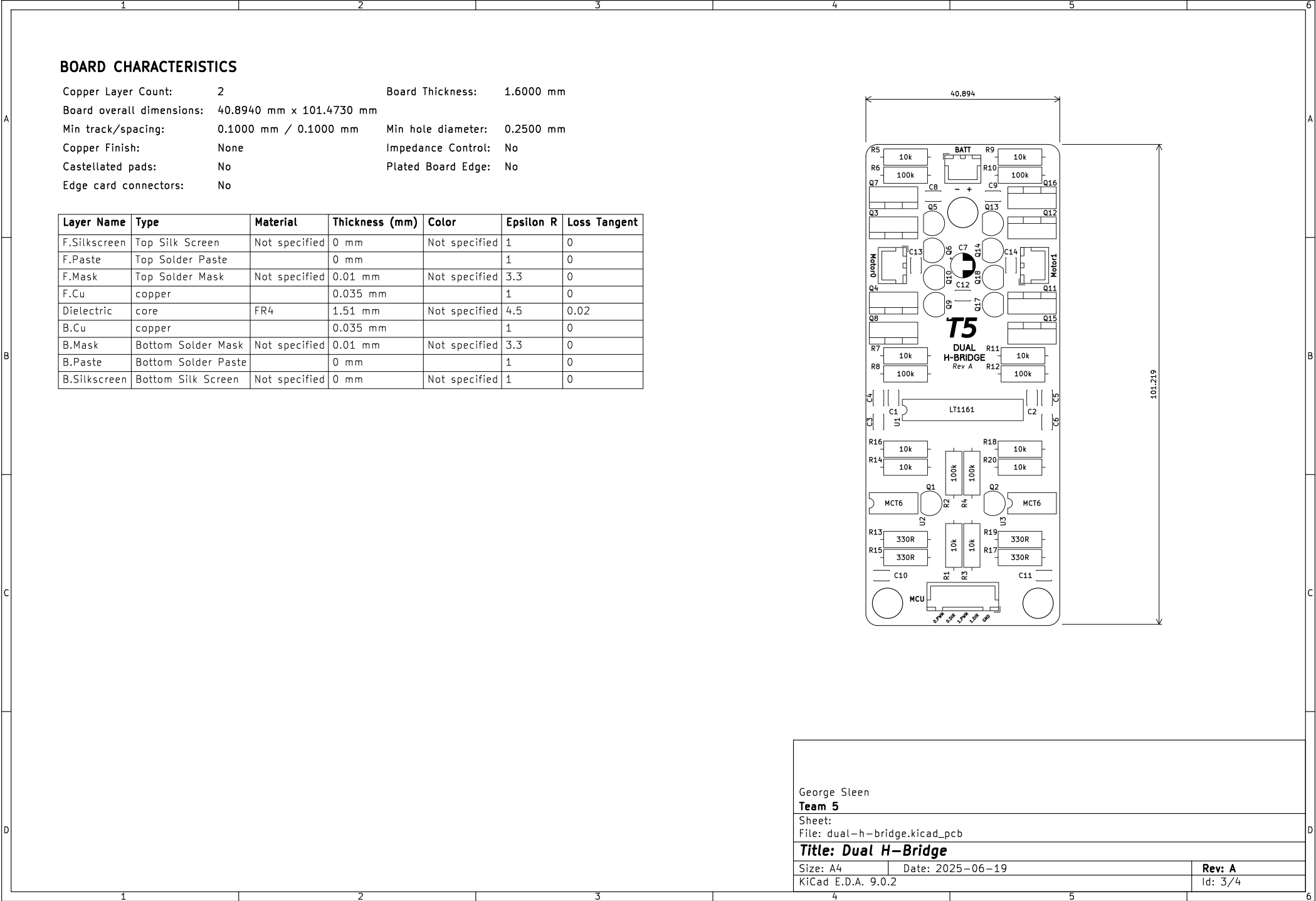
10k

C11

101.219

George SleenTeam 5Sheet:File: dual-h-bridge.kicad_pcbTitle: Dual H-BridgeSize: A4Date: 2025-06-19KiCad E.D.A. 9.0.2

Rev: AId: 3/4

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